

IEEE P802.3ck Ad Hoc meeting – October 24, 2018

Prepared by Kent Lusted

Proposed Agenda:

- Approval of the Agenda
- Approve 3 October ad hoc minutes
- IEEE Patent Policy reminder:
 - <http://www.ieee802.org/3/patent.html>
- IEEE Participation Requirements reminder
- Logistics for November Plenary meeting
- .3ck Ad Hoc –
 - “Towards Package Baseline Proposal for 100GEL”, Liav Ben-Artzi
 - “DFE-based Model vs FFE-based model for Reference Rx of COM”, Yasuo Hidaka
 - “Preliminary COM Results for Two Reference Receiver Models”, Louis Lu
 - “100G C2C Consideration”, Ali Ghiasi

Presentations posted at: <http://www.ieee802.org/3/cd/public/adhoc/archive/index.html>

Meeting began at ~7:05 a.m. Pacific by Beth Kochuparambil.

Meeting began with the agenda presentation:

http://www.ieee802.org/3/ck/public/adhoc/oct24_18/agenda_181024a_3ck_adhoc.pdf

The ad hoc chair reminded participants to indicate full names and employer/affiliation correctly for the meeting minutes. Reminded participants to mute lines when not speaking and reviewed the steps to unmute.

Showed the links to the IEEE P802.3cd Task Force ad hoc page and the email reflector.

Presented the proposed agenda and asked if there was objection as written. The agenda was approved by the ad hoc.

Asked if there were comments regarding the posted minutes for the October 3 ad hoc meeting. No one responded. The minutes were approved by the ad hoc.

Reminded participants of the IEEE patent policy. She asked if anyone was unfamiliar with the IEEE patent policy. No one responded.

Reminded participants of the IEEE Participation Requirements and showed the slide with the Participation requirements. She asked if anyone was unfamiliar with the IEEE Participation Requirements. No one responded.

Agenda Items

P802.3ck Task Force update, Beth Kochuparambil

- Presentation requests are due Friday, November 2, AoE.
- Presentation submissions are due 5pm Pacific, Wednesday, 7 November.
- Task force meets the week of November 12, 2018 at the IEEE 802.3 Plenary in Bangkok, Thailand.
- Meeting dates will be Tuesday afternoon thru Thursday morning.
- Task Force working towards baseline proposals.
- Next set of ad hocs will be Dec 5, 12, 19 and Jan 2.

Presentation #1:

“Towards Package Baseline Proposal for 100GEL” -- Liav Ben-Artzi

See: http://www.ieee802.org/3/ck/public/adhoc/oct24_18/benartsi_3ck_adhoc_01a_102418.pdf

- Updated version ‘01a’ with graphics and summary slide. Chair asked if there was an update. no objection.
- Discussed keeping the 12mm package models until there is analysis on the copper cable cases.
- The 30mm package loss is ~5 dB. Die contribution ($C_d = 110$ fF) adds ~2dB.

Presentation #2:

“DFE-based Model vs FFE-based model for Reference Rx of COM ” – Yasuo Hidaka

See: http://www.ieee802.org/3/ck/public/adhoc/oct24_18/hidaka_3ck_adhoc_01_102418.pdf

- Discussed the results shown on slide 9. There is concern of error propagation due to the large DFE tap weights.
- ADC quantization noise is not included in the COM analysis and will likely impact the results.

Presentation #3:

“Preliminary COM Results for Two Reference Receiver Models ” – Yunchun Louis Lu

See: http://www.ieee802.org/3/ck/public/adhoc/oct24_18/lu_3ck_adhoc_01_102418.pdf

- Discussed the results on slide 4 and the impact of noise on the results.

Presentation #4:

“100G C2C Consideration ” – Ali Ghiasi

See: http://www.ieee802.org/3/ck/public/adhoc/oct24_18/ghiasi_3ck_adhoc_01_102418.pdf

- Discussed the C2C reach assumptions of 200-250mm on slide 5.
- Discussed the BER implications on the C2C interface.

The ad hoc meeting ended at ~9 a.m. Pacific.

List of attendees (captured from Webex tool)

<u>Name</u>	<u>Affiliation</u>	<u>Employed by</u>
Adam Healey	Broadcom	Broadcom
Alexander Rysin	Mellanox	Mellanox
Ali Ghiasi	GhiasiQuantum LLC	GhiasiQuantum LLC
Andy Zambell	Amphenol	Amphenol
Arturo Pachon	TE Connectivity	TE Connectivity
Beth Kochuparambil	Cisco	Cisco
Bill Kirkland	Semtech	Semtech
Biman Chattopadhyay	Synopsys	Synopsys
Brandon Gore	Samtec	Samtec
Brian Holden	Kandou	Kandou
Burrell Best	Samtec	Samtec
Dave Lewis	Lumentum	Lumentum
David Malicoat	Senko & Aquantia	Malicoat Networking Solutions
David Ofelt	Juniper	Juniper

David Rennie	Synopsys	Synopsys
Derek Cassidy	BT	BT
Gary Nicholl	Cisco	Cisco
Geoff Zhang	Xilinx	Xilinx
Greg LeCheminant	Keysight	Keysight Technologies
Henry Poelstra	Teledyne	Teledyne
Howard Heck	Intel	Intel
Inho Kim	Marvell	Marvell
Jayen Desai	Intel	Intel
Jeff Slavick	Broadcom	Broadcom
Jeff Twombly	Credo	Credo
Jeffery Maki	Juniper	Juniper
Jeremy Stephens	Intel	Intel
John D'Ambrosia	FutureWei (Subsidiary of Huawei)	FutureWei (Subsidiary of Huawei)
John Ewen	Globalfoundries	Globalfoundries
Karen Liu	Kaiam	Kaiam
Ken Jackson	Sumitomo	Sumitomo

Kent Lusted	Intel	Intel
Liav Ben-Artzi	Marvell	Marvell
Margaret	Cadence	Cadence
Mark Gustlin	Xilinx	Xilinx
Mark Nowell	Cisco	Cisco
Matt Brown	Macom	Macom
Mau-Lin Wu	Mediatek	Mediatek
Mike Dudek	Cavium	Cavium
Nathan Tracy	TE Connectivity	TE Connectivity
Pete Anslow	Ciena	Ciena
Phil Sun	Credo	Credo
Pirooz Tooyserkani	Cisco	Cisco
Raymond Nering	Cisco	Cisco
Rich Mellitz	Samtec	Samtec
Rick Pimpinella	Panduit	Panduit
Rita Horner	Synopsys	Synopsys
Sam Kocsis	Amphenol	Amphenol
Shawn Nicholl	Xilinx	Xilinx
Shimon	Axalume	Axalume

Steve Sekel	Keysight	Keysight
Steve Trowbridge	Nokia	Nokia
Takeshi Nishimura	Yamaichi Electronics, USA	Yamaichi Electronics, USA
Ted Sprague	Infinera	Infinera
Tom Palkert	Molex/Macom	Molex/Macom
Toshiaki Sakai	Socionext	Socionext
Upen Kareti	Cisco	Cisco
Vittal Balasubramanian	Innovium	Innovium
Yang Zhiwei	ZTE	ZTE
Yasuo Hidaka	Independent	Independent
Yuchun(Louis) Lu	Huawei	Huawei
Zvi Rechtman	Mellanox	Mellanox